



20V P-Channel Trench Power MOSFET

General Description

The SJP20P110 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -2.5V. This device is suitable for use as a wide variety of applications.

Features

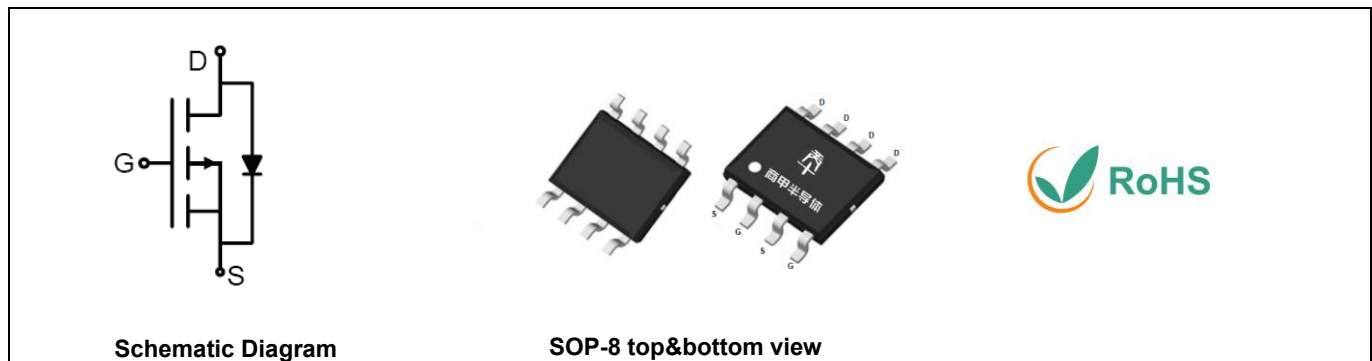
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Key Performance Parametes

Parameter	Value	Unit
V_{DS}	-20	V
$R_{DS(ON_TYP)}$	9.5	m Ω
I_D	-14.5	A
Q_G	14	nC



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJP20P110	SJP20P110	SOP-8	Tape	\	\	4000 Pcs

Table 1. Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	-20	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 12	V
I_D	Drain Current-Continuous($T_A=25^\circ\text{C}$)	-14.5	A
	Drain Current-Continuous($T_A=100^\circ\text{C}$)	-9	A
I_{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	58	A
P_D	Maximum Power Dissipation($T_A=25^\circ\text{C}$)	3.6	W
	Maximum Power Dissipation($T_A=100^\circ\text{C}$)	1.4	W
E_{AS}	Avalanche energy (Note 2)	72	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ\text{C}$

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	34.6		$^\circ\text{C}/\text{W}$



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Table 3. Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
B _{VDSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	-20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-20V, V _{GS} =0V T _J =25°C			-1	μA
		V _{DS} =-20V, V _{GS} =0V T _J =125°C			100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	-1		-0.5	V
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-4A		18		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-4A T _J =25°C		9.5	11.9	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-2.5V, I _D =-2A T _J =25°C		12.5	16.6	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-10V, V _{GS} =0V, f=1.0MHz		2410		pF
C _{oss}	Output Capacitance			256		pF
C _{rss}	Reverse Transfer Capacitance			229		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		4.9		Ω
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =-4.5V, V _{DS} =-10V, R _L =2.5Ω, R _{GEN} =3Ω		13		nS
t _r	Turn-on Rise Time			32		nS
t _{d(off)}	Turn-Off Delay Time			27		nS
t _f	Turn-Off Fall Time			9		nS
Q _g	Total Gate Charge	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-4A		14		nC
Q _{gs}	Gate-Source Charge			1.2		nC
Q _{gd}	Gate-Drain Charge			4.8		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				-14.5	A
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =-4A			-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-4A, dI/dt=100A/μs		160		ns
Q _{rr}	Reverse Recovery Charge	I _F =-4A, dI/dt=100A/μs		60		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

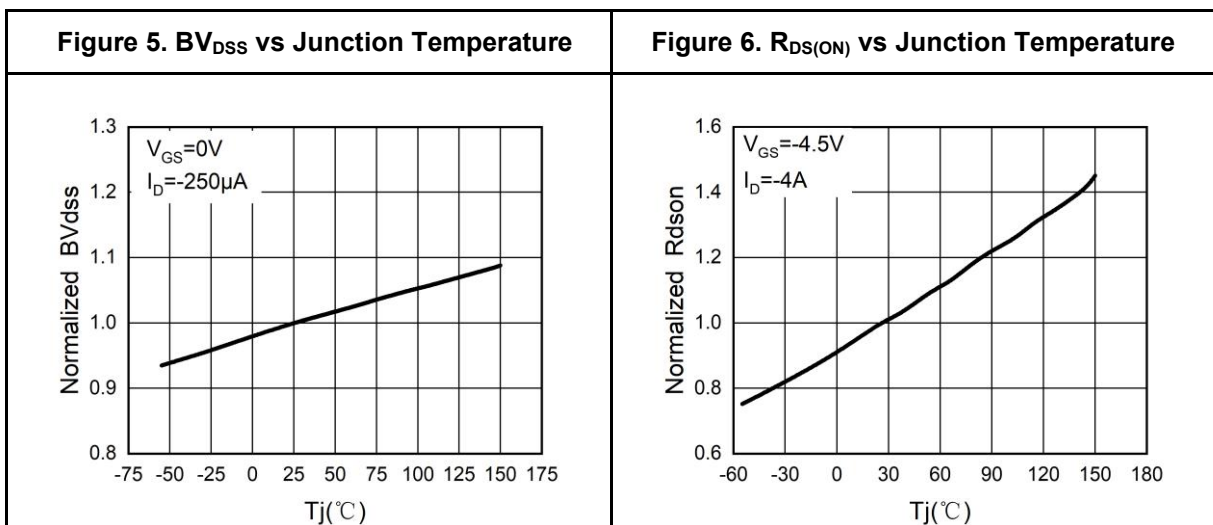
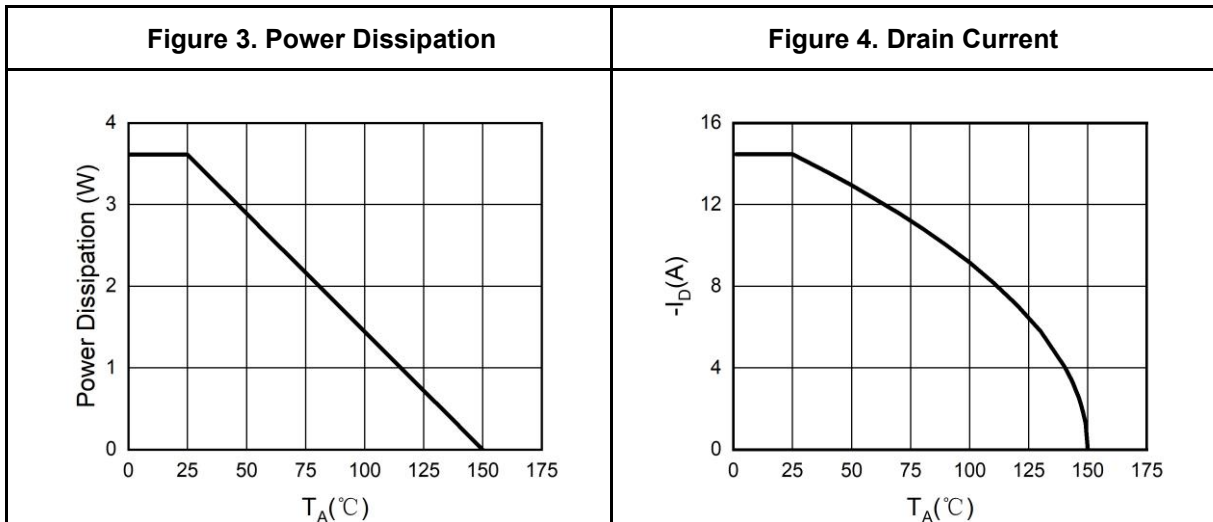
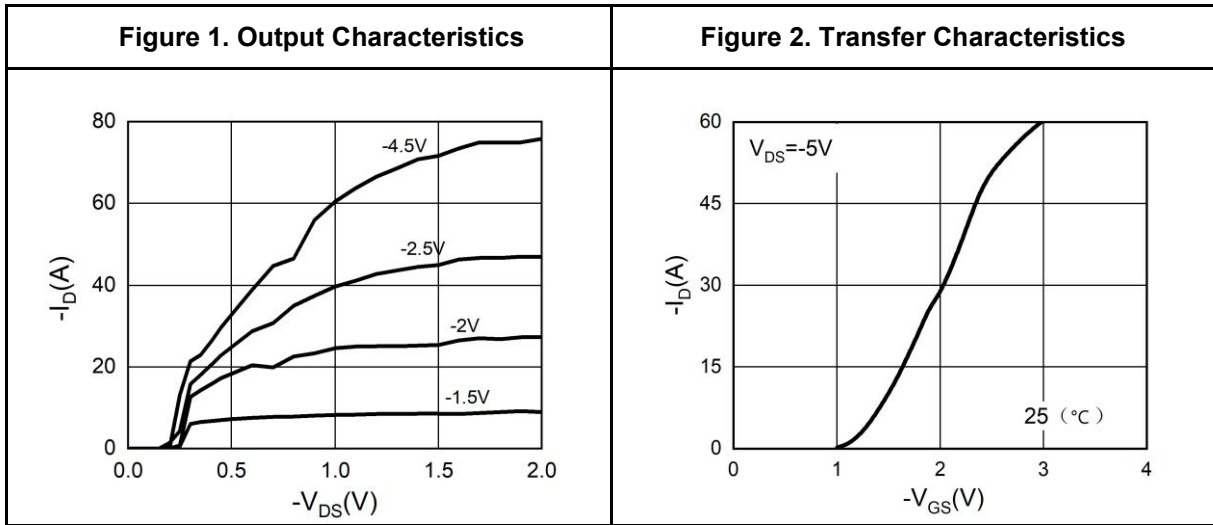
Notes 2.EAS condition: T_J=25°C, V_{DD}=-12V, V_G=-10V, R_g=25Ω, L=0.5mH.

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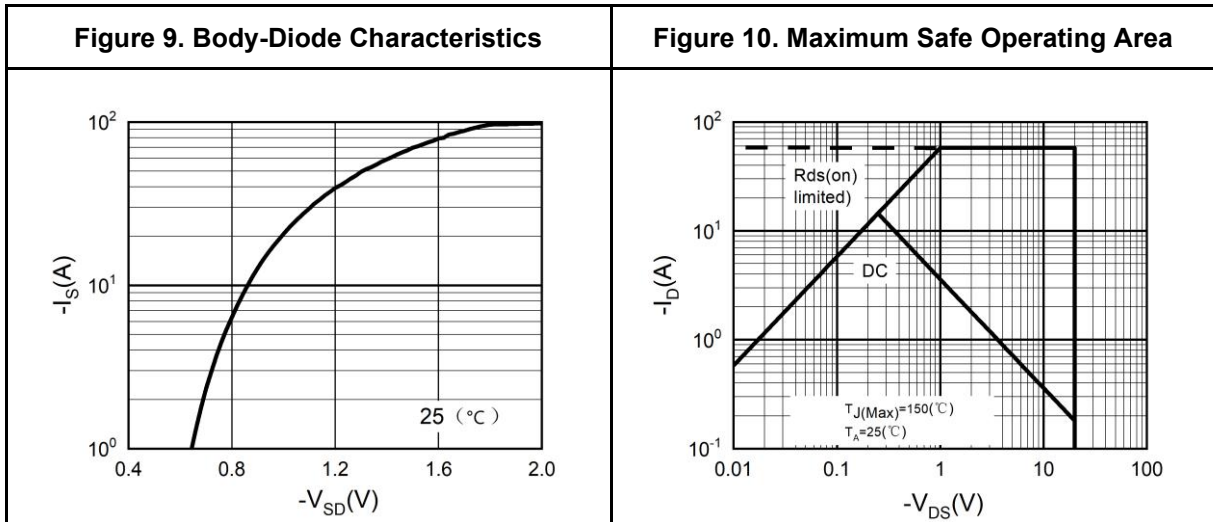
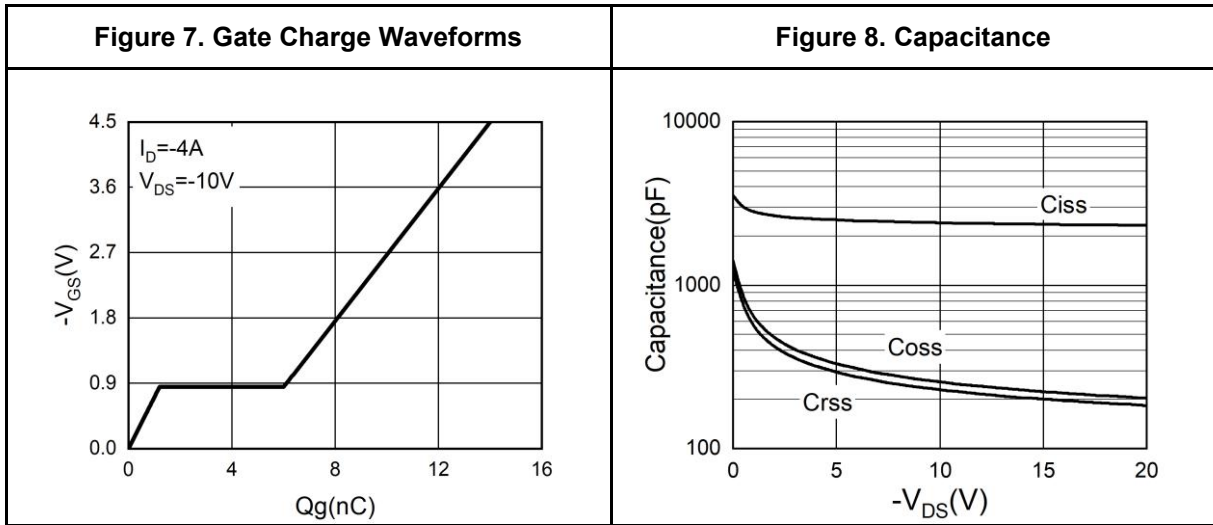
Typical Electrical And Thermal Characteristics (Curves)





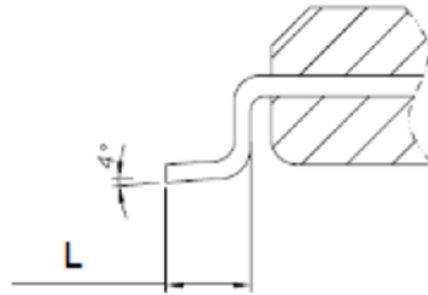
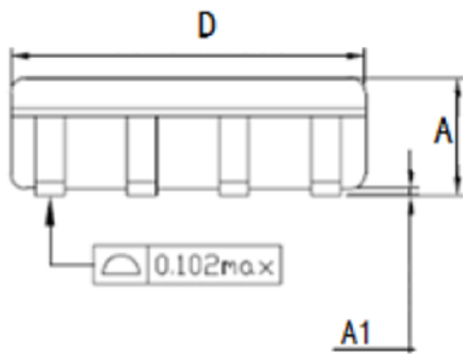
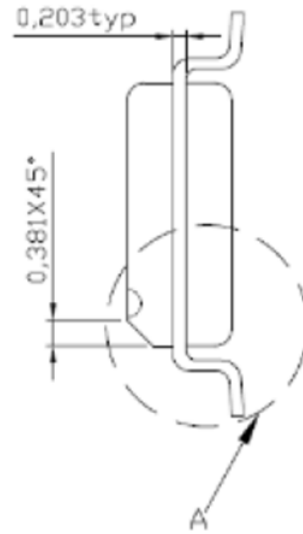
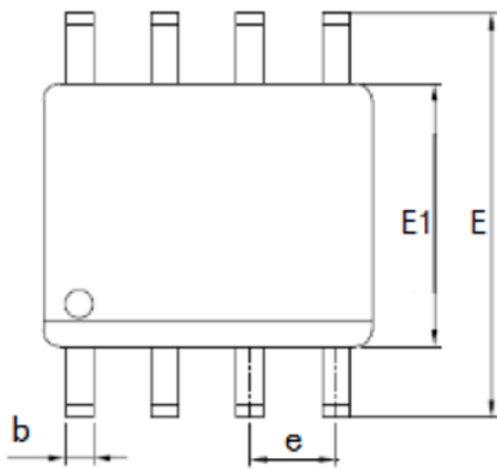
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Typical Electrical And Thermal Characteristics (Curves)





SOP-8 Package Information



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SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A1	0.00	0.05	0.10
A2	0.90	1.00	1.10
b	0.30	0.40	0.50
c	0.08	0.10	0.15
D	2.80	2.90	3.00
E	1.20	1.30	1.40
E1	2.30	2.40	2.50
L	0.30	0.40	0.50
θ	0°	5°	10°
L1	0.55 REF		
e	0.95 BSC		
e1	1.90 REF		



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